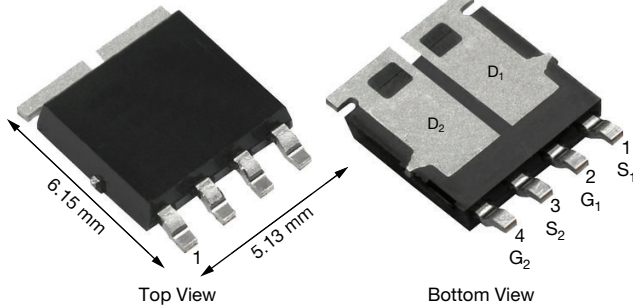
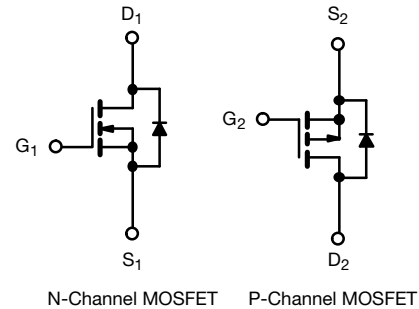


# Automotive N- and P-Channel 60 V (D-S) 175 °C MOSFET

**PowerPAK® SO-8L Dual**

**FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>G</sub> and UIS tested
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

 AUTOMOTIVE  
GRADE

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

**PRODUCT SUMMARY**

	N-CHANNEL	P-CHANNEL
V <sub>DS</sub> (V)	60	-60
R <sub>DS(on)</sub> (Ω) at V <sub>GS</sub> = ± 10 V	0.0120	0.0526
R <sub>DS(on)</sub> (Ω) at V <sub>GS</sub> = ± 4.5 V	0.0160	0.0755
I <sub>D</sub> (A)	30	-18
Configuration	N- and p-pair	
Package	PowerPAK SO-8L	

**ABSOLUTE MAXIMUM RATINGS** (T<sub>C</sub> = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	N-CHANNEL	P-CHANNEL	UNIT	
Drain-source voltage	V <sub>DS</sub>	60	-60	V	
Gate-source voltage	V <sub>GS</sub>	± 20			
Continuous drain current	I <sub>D</sub>	T <sub>C</sub> = 25 °C	30 <sup>a</sup>	-18	A
		T <sub>C</sub> = 125 °C	24.6	-10.3	
Continuous source current (diode conduction) <sup>a</sup>	I <sub>S</sub>	30	-30		
Pulsed drain current <sup>b</sup>	I <sub>DM</sub>	120	-50		
Single pulse avalanche current	I <sub>AS</sub>	L = 0.1 mH	23	-24	mJ
Single pulse avalanche Energy			E <sub>AS</sub>	26.4	
Maximum power dissipation <sup>b</sup>	P <sub>D</sub>	T <sub>C</sub> = 25 °C	34	34	W
		T <sub>C</sub> = 125 °C	11	11	
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175		°C	
Soldering recommendations (peak temperature) <sup>d, e</sup>		260			

**THERMAL RESISTANCE RATINGS**

PARAMETER	SYMBOL	N-CHANNEL	P-CHANNEL	UNIT
Junction-to-ambient	R <sub>thJA</sub>	85	85	°C/W
Junction-to-case (drain)				

**Notes**

- Package limited
- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %
- When mounted on 1" square PCB (FR4 material)
- See solder profile ([www.vishay.com/doc?73257](http://www.vishay.com/doc?73257)). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



<b>SPECIFICATIONS</b> ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		N-Ch	60	-	-
		$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$		P-Ch	-60	-	-
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		N-Ch	1.5	2	2.5
		$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$		P-Ch	-1.5	-2	-2.5
Gate-source leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$		N-Ch	-	-	$\pm 100$
				P-Ch	-	-	$\pm 100$
Zero gate voltage drain current	$I_{DSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}$	N-Ch	-	-	1
		$V_{GS} = 0\text{ V}$	$V_{DS} = -60\text{ V}$	P-Ch	-	-	-1
		$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}, T_J = 125\text{ }^\circ\text{C}$	N-Ch	-	-	50
		$V_{GS} = 0\text{ V}$	$V_{DS} = -60\text{ V}, T_J = 125\text{ }^\circ\text{C}$	P-Ch	-	-	-50
		$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}, T_J = 175\text{ }^\circ\text{C}$	N-Ch	-	-	150
		$V_{GS} = 0\text{ V}$	$V_{DS} = -60\text{ V}, T_J = 175\text{ }^\circ\text{C}$	P-Ch	-	-	-150
On-state drain current <sup>a</sup>	$I_{D(on)}$	$V_{GS} = 10\text{ V}$	$V_{DS} \geq 5\text{ V}$	N-Ch	10	-	-
		$V_{GS} = -10\text{ V}$	$V_{DS} \leq 5\text{ V}$	P-Ch	-10	-	-
Drain-source on-state resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 10\text{ A}$	N-Ch	-	0.0099	0.0120
		$V_{GS} = -10\text{ V}$	$I_D = -10\text{ A}$	P-Ch	-	0.0432	0.0526
		$V_{GS} = 10\text{ V}$	$I_D = 10\text{ A}, T_J = 125\text{ }^\circ\text{C}$	N-Ch	-	-	0.0164
		$V_{GS} = -10\text{ V}$	$I_D = -10\text{ A}, T_J = 125\text{ }^\circ\text{C}$	P-Ch	-	-	0.0872
		$V_{GS} = 10\text{ V}$	$I_D = 10\text{ A}, T_J = 175\text{ }^\circ\text{C}$	N-Ch	-	-	0.0185
		$V_{GS} = -10\text{ V}$	$I_D = -10\text{ A}, T_J = 175\text{ }^\circ\text{C}$	P-Ch	-	-	0.1072
		$V_{GS} = 4.5\text{ V}$	$I_D = 8\text{ A}$	N-Ch	-	0.0133	0.0160
		$V_{GS} = -4.5\text{ V}$	$I_D = -8\text{ A}$	P-Ch	-	0.0628	0.0755
Forward transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 10\text{ A}$		N-Ch	-	56	-
		$V_{DS} = -15\text{ V}, I_D = -10\text{ A}$		P-Ch	-	16	-
<b>Dynamic <sup>b</sup></b>							
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	N-Ch	-	1205	1650
		$V_{GS} = 0\text{ V}$	$V_{DS} = -25\text{ V}, f = 1\text{ MHz}$	P-Ch	-	1195	1650
Output capacitance	$C_{oss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	N-Ch	-	560	800
		$V_{GS} = 0\text{ V}$	$V_{DS} = -25\text{ V}, f = 1\text{ MHz}$	P-Ch	-	162	250
Reverse transfer capacitance	$C_{rss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	N-Ch	-	29	42
		$V_{GS} = 0\text{ V}$	$V_{DS} = -25\text{ V}, f = 1\text{ MHz}$	P-Ch	-	102	150
Total gate charge <sup>c</sup>	$Q_g$	$V_{GS} = 10\text{ V}$	$V_{DS} = 30\text{ V}, I_D = 10\text{ A}$	N-Ch	-	18	30
		$V_{GS} = -10\text{ V}$	$V_{DS} = -30\text{ V}, I_D = -10\text{ A}$	P-Ch	-	29	45
Gate-source charge <sup>c</sup>	$Q_{gs}$	$V_{GS} = 10\text{ V}$	$V_{DS} = 30\text{ V}, I_D = 10\text{ A}$	N-Ch	-	4	-
		$V_{GS} = -10\text{ V}$	$V_{DS} = -30\text{ V}, I_D = -10\text{ A}$	P-Ch	-	5	-
Gate-drain charge <sup>c</sup>	$Q_{gd}$	$V_{GS} = 10\text{ V}$	$V_{DS} = 30\text{ V}, I_D = 10\text{ A}$	N-Ch	-	2	-
		$V_{GS} = -10\text{ V}$	$V_{DS} = -30\text{ V}, I_D = -10\text{ A}$	P-Ch	-	7	-
Gate resistance	$R_g$	$f = 1\text{ MHz}$		N-Ch	0.23	0.46	0.70
				P-Ch	1.02	2.06	3.10



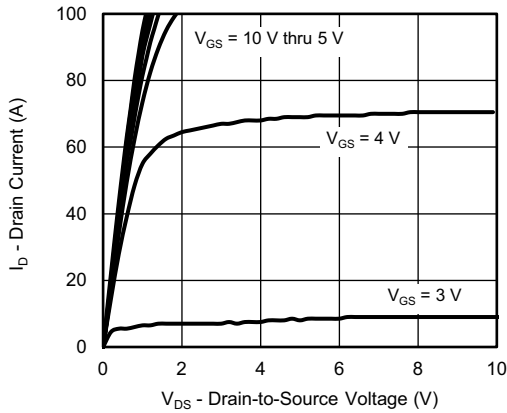
<b>SPECIFICATIONS</b> ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Turn-on delay time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = 30\text{ V}, R_L = 3\text{ }\Omega,$ $I_D \cong 10\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$	N-Ch	-	12	20	ns
		$V_{DD} = -30\text{ V}, R_L = 3\text{ }\Omega,$ $I_D \cong -10\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$	P-Ch	-	11	20	
Rise time <sup>c</sup>	$t_r$	$V_{DD} = 30\text{ V}, R_L = 3\text{ }\Omega,$ $I_D \cong 10\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$	N-Ch	-	4	10	
		$V_{DD} = -30\text{ V}, R_L = 3\text{ }\Omega,$ $I_D \cong -10\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$	P-Ch	-	6	10	
Turn-off delay time <sup>c</sup>	$t_{d(off)}$	$V_{DD} = 30\text{ V}, R_L = 3\text{ }\Omega,$ $I_D \cong 10\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$	N-Ch	-	20	35	
		$V_{DD} = -30\text{ V}, R_L = 3\text{ }\Omega,$ $I_D \cong -10\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$	P-Ch	-	27	45	
Fall time <sup>c</sup>	$t_f$	$V_{DD} = 30\text{ V}, R_L = 3\text{ }\Omega,$ $I_D \cong 10\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$	N-Ch	-	4	10	
		$V_{DD} = -30\text{ V}, R_L = 3\text{ }\Omega,$ $I_D \cong -10\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$	P-Ch	-	5	10	
<b>Source-Drain Diode Ratings and Characteristics</b> <sup>b</sup>							
Pulsed current <sup>a</sup>	$I_{SM}$		N-Ch	-	-	120	A
			P-Ch	-	-	-50	
Forward voltage	$V_{SD}$	$I_S = 10\text{ A}, V_{GS} = 0\text{ V}$	N-Ch	-	0.83	1.2	V
		$I_S = -10\text{ A}, V_{GS} = 0\text{ V}$	P-Ch	-	-0.88	-1.2	
Body diode reverse recovery time	$t_{rr}$	$I_F = 10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	N-Ch	-	37	80	ns
		$I_F = -10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	P-Ch	-	39	80	
Body diode reverse recovery charge	$Q_{rr}$	$I_F = 10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	N-Ch	-	24	50	nC
		$I_F = -10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	P-Ch	-	58	120	
Reverse recovery fall time	$t_a$	$I_F = 10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	N-Ch	-	14	-	ns
		$I_F = -10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	P-Ch	-	29	-	
Reverse recovery rise time	$t_b$	$I_F = 10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	N-Ch	-	23	-	
		$I_F = -10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	P-Ch	-	10	-	
Body diode peak reverse recovery current	$I_{RM(REC)}$	$I_F = 10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	N-Ch	-	-1.3	-	A
		$I_F = -10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	P-Ch	-	-3.3	-	

**Notes**

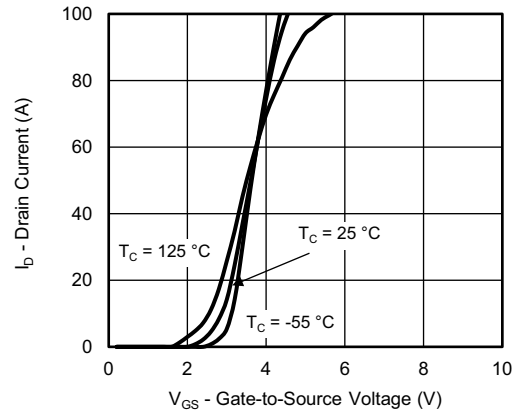
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

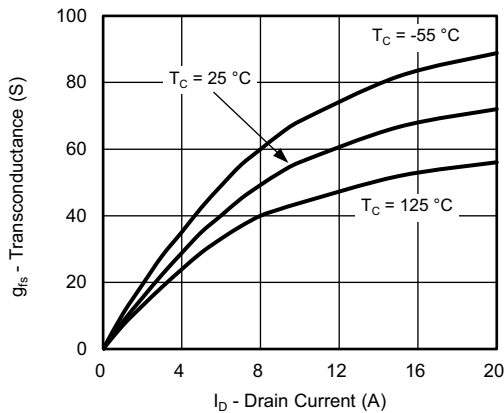
**N-CHANNEL TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



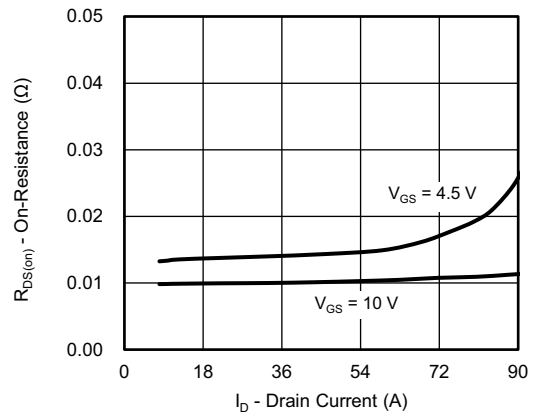
**Output Characteristics**



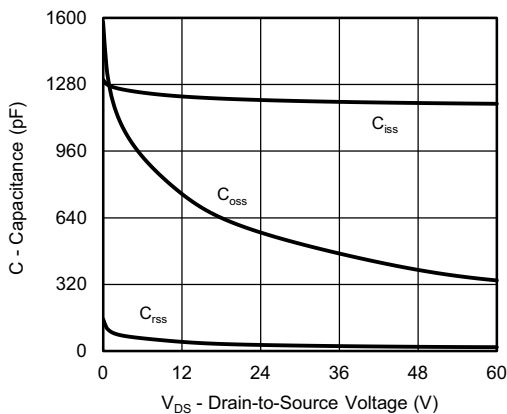
**Transfer Characteristics**



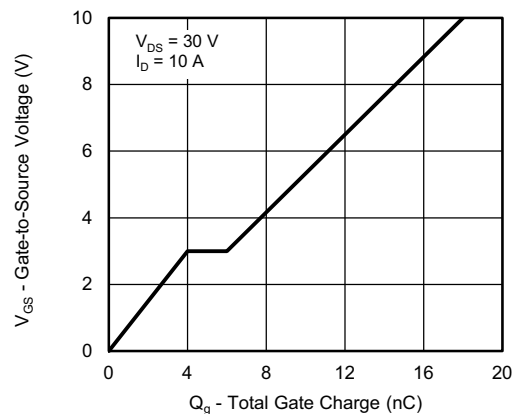
**Transconductance**



**On-Resistance vs. Drain Current**



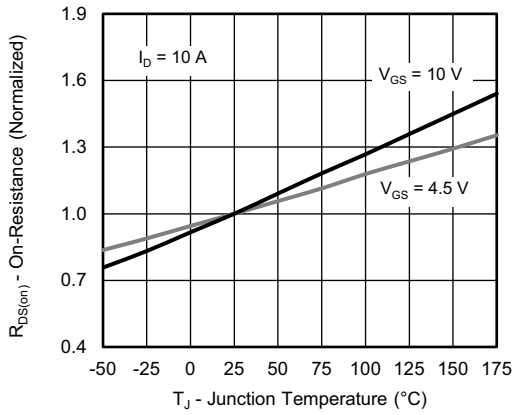
**Capacitance**



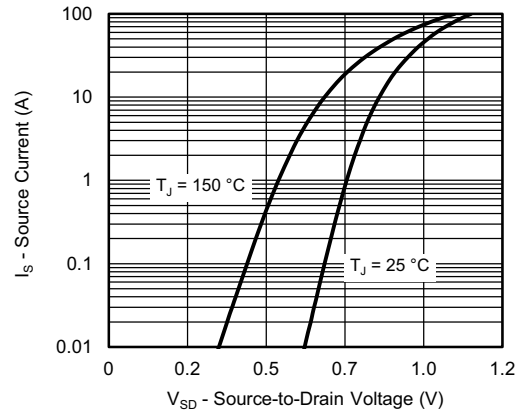
**Gate Charge**



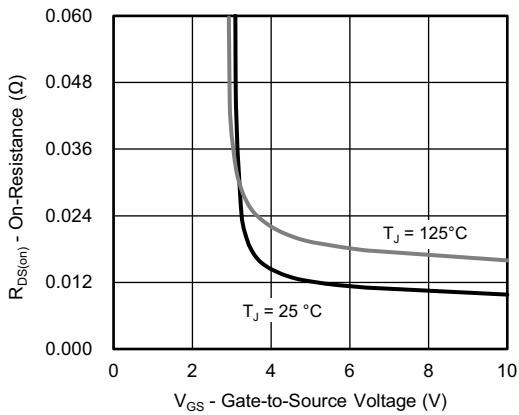
**N-CHANNEL TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



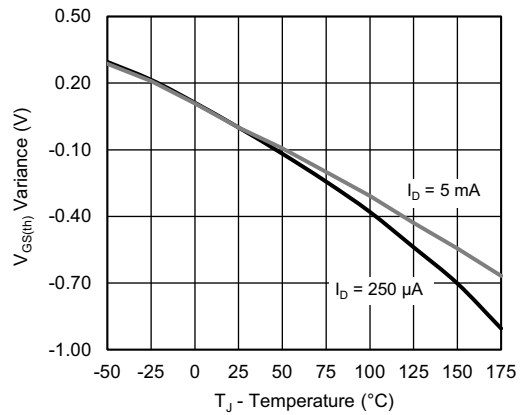
**On-Resistance vs. Junction Temperature**



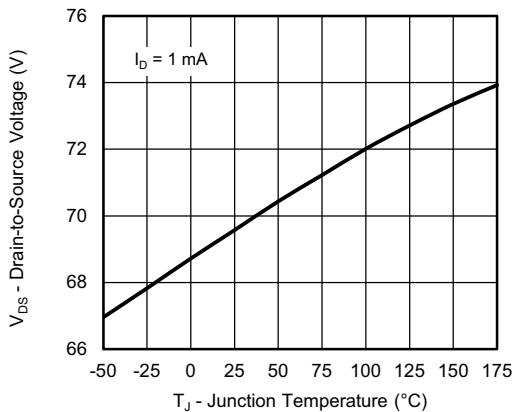
**Source Drain Diode Forward Voltage**



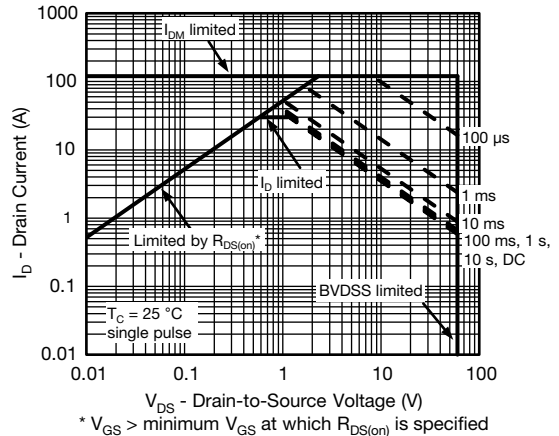
**On-Resistance vs. Gate-to-Source Voltage**



**Threshold Voltage**

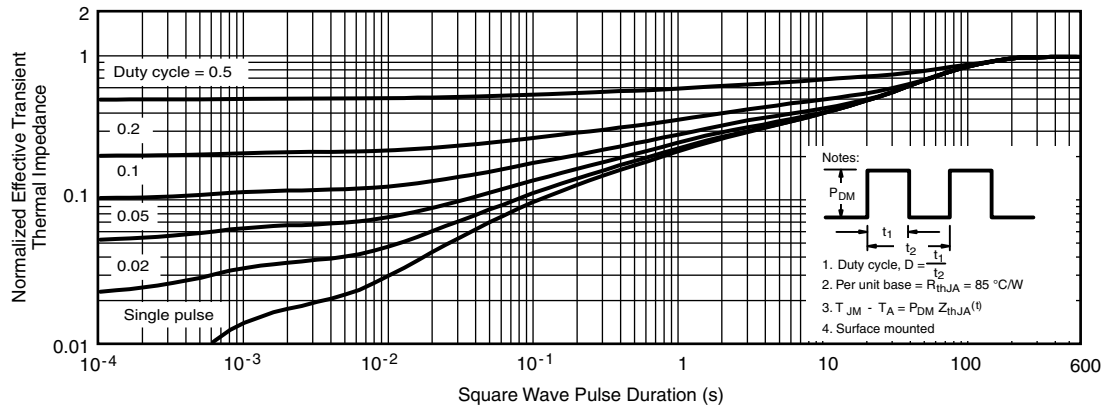


**Drain Source Breakdown vs. Junction Temperature**

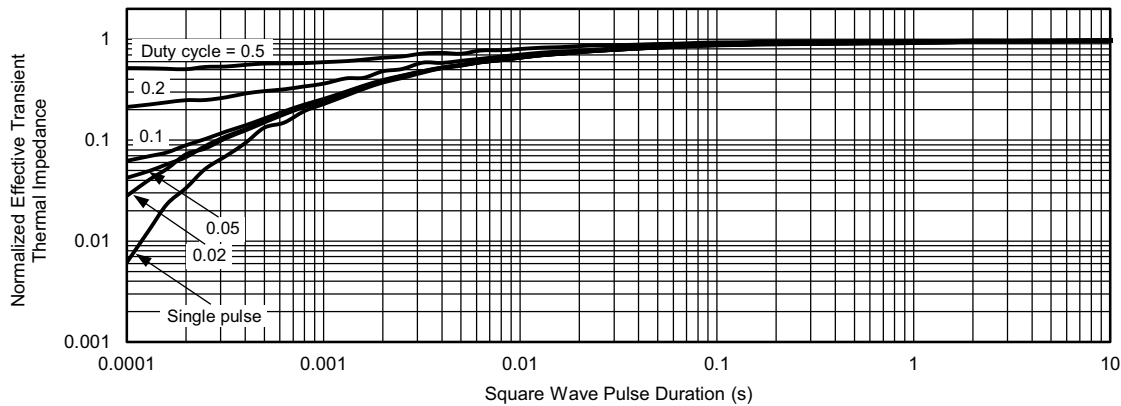


**Safe Operating Area**

**N-CHANNEL TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



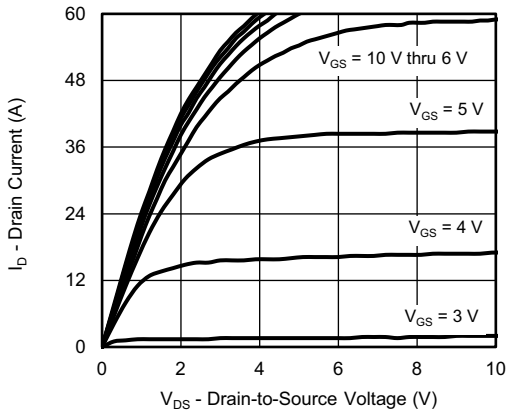
**Normalized Thermal Transient Impedance, Junction-to-Case**

**Note**

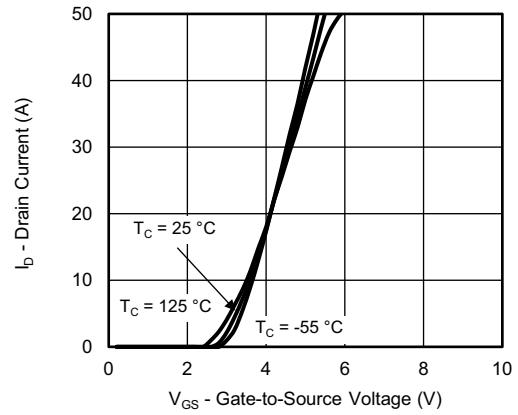
- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient ( $25\text{ }^\circ\text{C}$ )
  - Normalized Transient Thermal Impedance Junction-to-Case ( $25\text{ }^\circ\text{C}$ )
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions



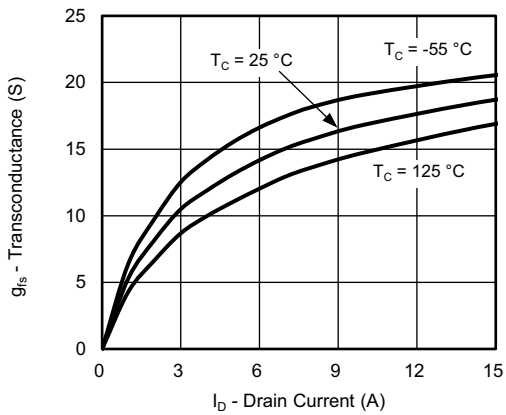
**P-CHANNEL TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



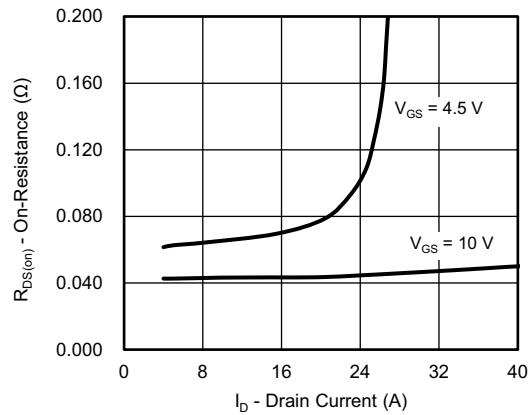
**Output Characteristics**



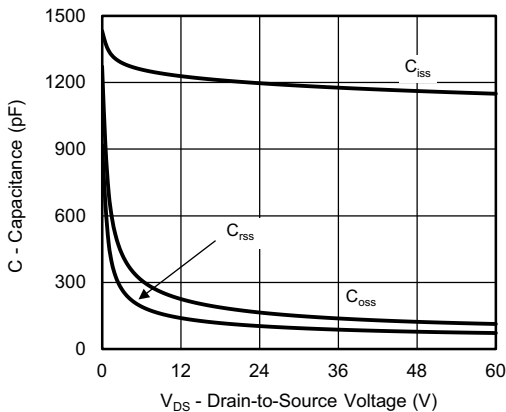
**Transfer Characteristics**



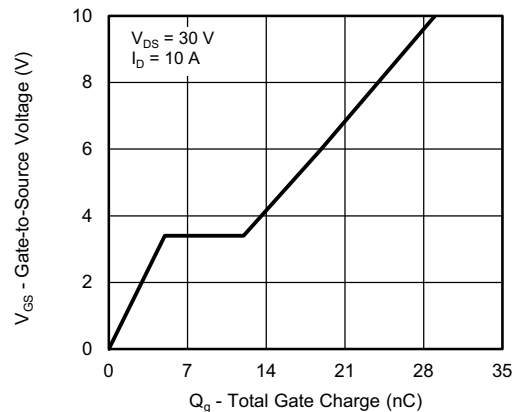
**Transconductance**



**On-Resistance vs. Drain Current**



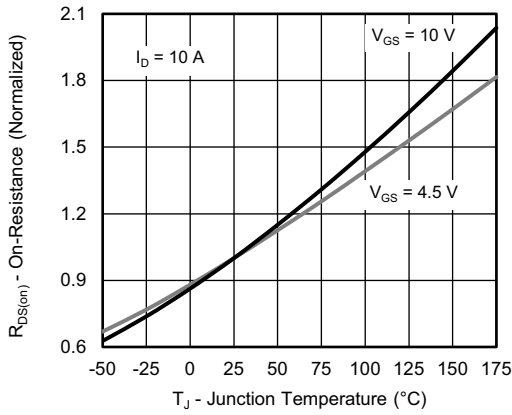
**Capacitance**



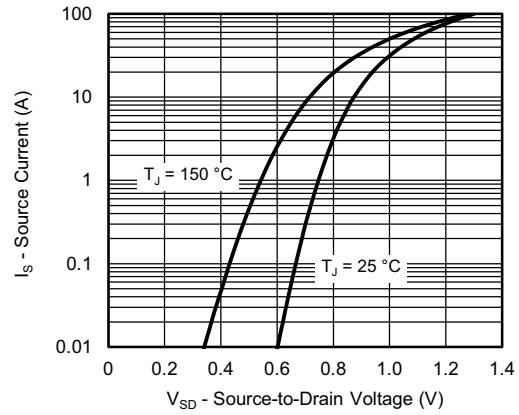
**Gate Charge**



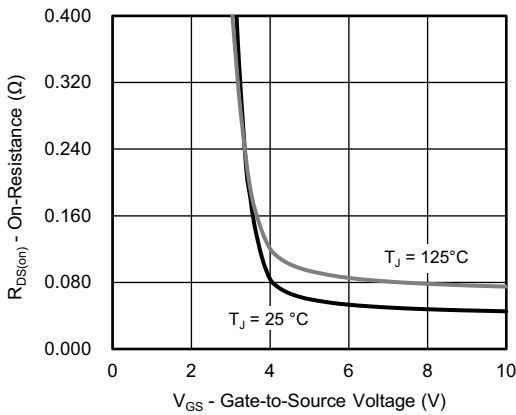
P-CHANNEL TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



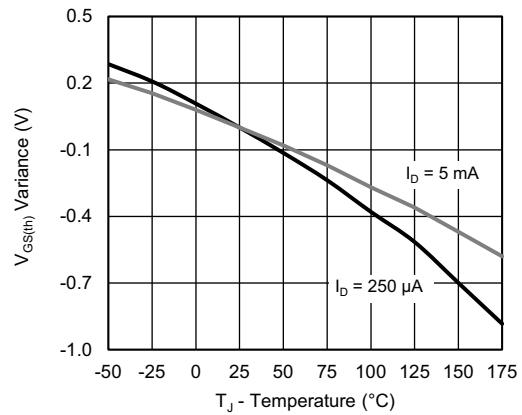
Threshold Voltage



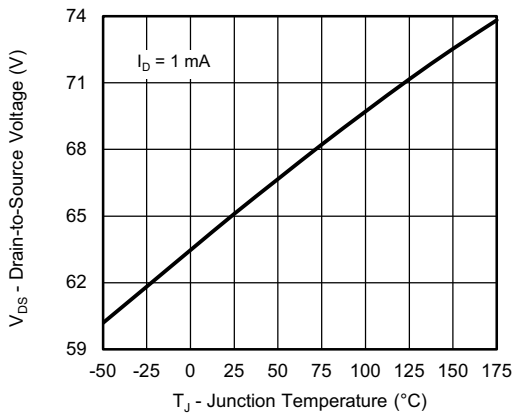
Source Drain Diode Forward Voltage



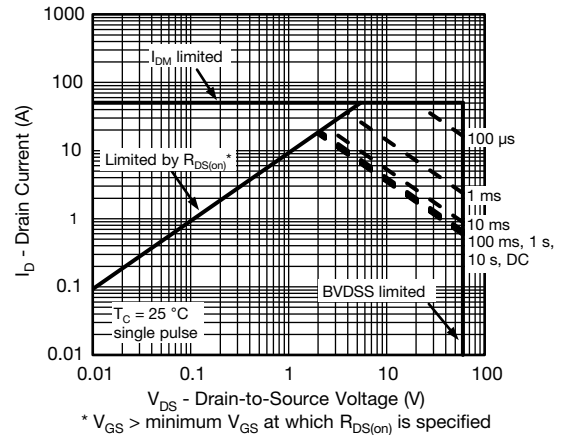
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



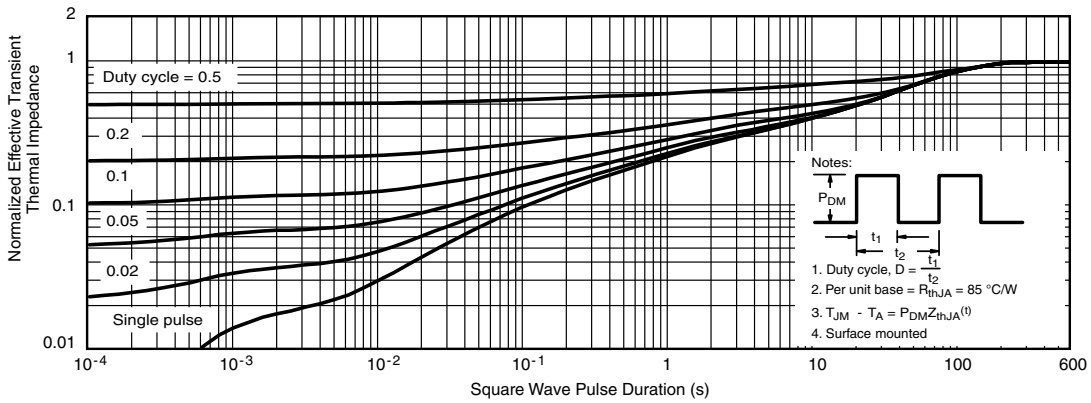
Drain Source Breakdown vs. Junction Temperature



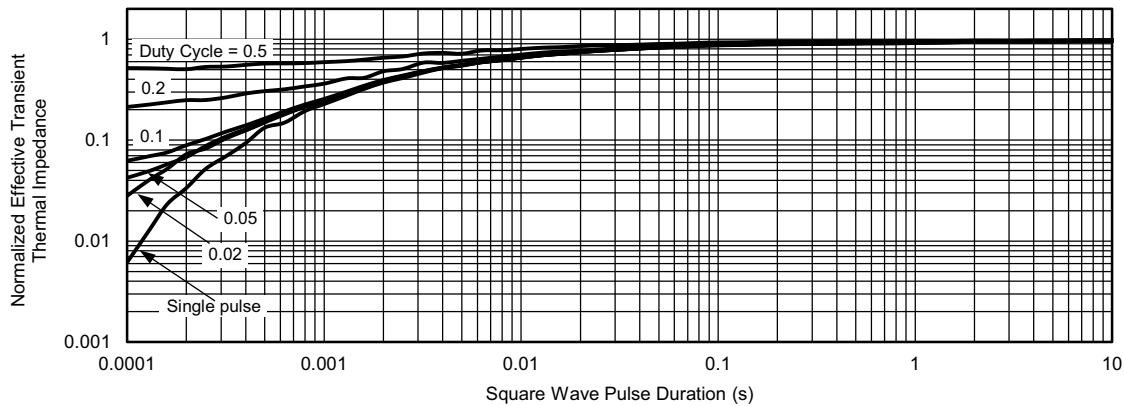
Safe Operating Area



**P-CHANNEL TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**Normalized Thermal Transient Impedance, Junction-to-Case**

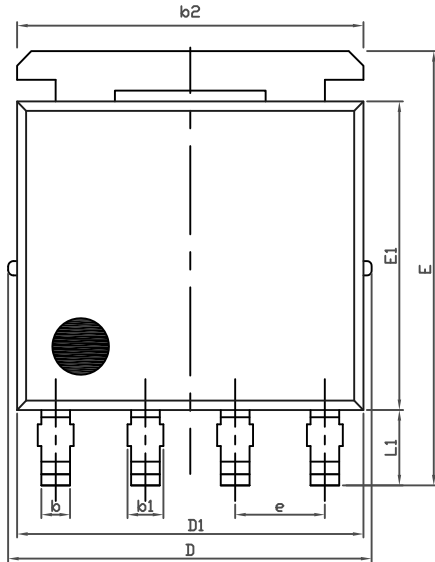
**Note**

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient ( $25\text{ }^\circ\text{C}$ )
  - Normalized Transient Thermal Impedance Junction-to-Case ( $25\text{ }^\circ\text{C}$ )
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

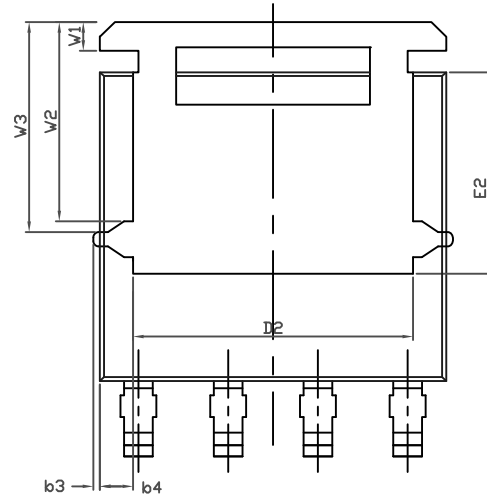
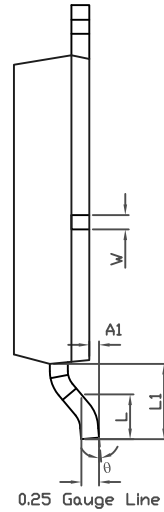
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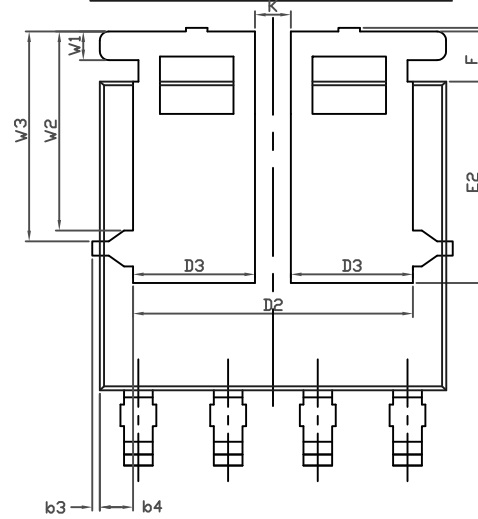
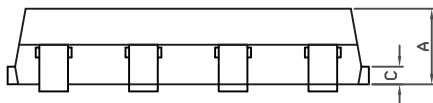
# PowerPAK® SO-8L Case Outline for AI Parts



TOPSIDE VIEW



BACKSIDE VIEW(SINGLE)



BACKSIDE VIEW(DUAL)



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.00	1.07	1.14	0.039	0.042	0.045
A1	0.00	-	0.127	0.00	-	0.005
b	0.33	0.41	0.48	0.013	0.016	0.019
b1	0.44	0.51	0.58	0.017	0.020	0.023
b2	4.80	4.90	5.00	0.189	0.193	0.197
b3	0.094			0.004		
b4	0.47			0.019		
c	0.20	0.25	0.30	0.008	0.010	0.012
D	5.00	5.13	5.25	0.197	0.202	0.207
D1	4.80	4.90	5.00	0.189	0.193	0.197
D2	3.86	3.96	4.06	0.152	0.156	0.160
D3	1.63	1.73	1.83	0.064	0.068	0.072
e	1.27 BSC			0.050 BSC		
E	6.05	6.15	6.25	0.238	0.242	0.246
E1	4.27	4.37	4.47	0.168	0.172	0.176
E2	2.75	2.85	2.95	0.108	0.112	0.116
F	-	-	0.15	-	-	0.006
L	0.62	0.72	0.82	0.024	0.028	0.032
L1	0.92	1.07	1.22	0.036	0.042	0.048
K	0.51			0.020		
W	0.23			0.009		
W1	0.41			0.016		
W2	2.82			0.111		
W3	2.96			0.117		
q	0°	-	10°	0°	-	10°

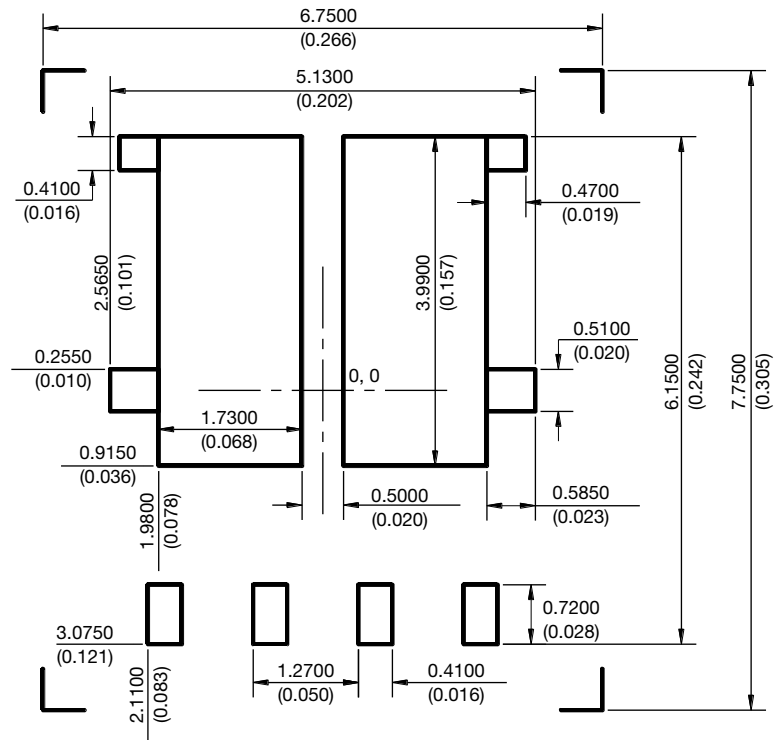
ECN: C15-1203-Rev. A, 07-Sep-15  
DWG: 6044

**Note**

- Millimeters will govern



**RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L DUAL**



Recommended Minimum Pads  
Dimensions in mm (inches)  
Keep-out 6.75 (0.266) x 7.75 (0.305)



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